

Title (en)

METHOD FOR PRODUCING AN ELECTRONIC COMPONENT

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES ELEKTRONISCHEN BAUTEILS

Title (fr)

PROCEDE DE PRODUCTION D'UN COMPOSANT ELECTRONIQUE

Publication

**EP 1456880 A2 20040915 (DE)**

Application

**EP 02791626 A 20021211**

Priority

- DE 0204529 W 20021211
- DE 10163084 A 20011220

Abstract (en)

[origin: WO03054957A2] The invention relates to an electronic component (1) and a method for producing the same. Said electronic component (1) comprises a semiconductor chip (2), a rewiring plate (3) and a plastic housing (4) which is divided into two plastic parts (23) arranged one on top of the other. A first layer (5) forming one of the plastic housing parts (23) has a relatively uneven surface which is smoothed by a second layer (6) forming the other plastic housing part (23), in such a way that the electronic component (1) is provided with a plastic housing (4) having smooth outer sides.

IPC 1-7

**H01L 23/31; H01L 21/56**

IPC 8 full level

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Citation (search report)

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DOCDB simple family (publication)

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